

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Previously Presented) A small footprint semiconductor device package comprising:

a plastic package body for enclosing a die, the plastic package body including a top coupled to a bottom through a plurality of sides;

a diepad supporting the die, the diepad having a first side and a second side opposite the first side;

a first lead integral with a first side of the diepad and in electrical and thermal communication with the die through the diepad, the first lead including an enclosed portion by the package body and in electrical communication with the die, and an exposed portion of the first lead extending from the side of the package body, folding back along the side of the package toward the bottom of the package at a first angle, and folding underneath the package bottom toward a center of the bottom of the package to form a first lead foot having a reverse gull wing shape, whereupon the portion of the first lead along the side of the package and the portion of the lead along the bottom of the package form an angle of less than 90° from each other and the first lead foot being inclined at a second angle relative to an underlying planar PC board to promote solder wetting; and

a second lead nonintegral with the second side of the diepad and in electrical communication with the die through a bondwire, the second lead including an enclosed portion by the package body and in electrical communication with the die, and an exposed portion of the second lead extending from the side of the package body, folding back along the side of the package toward the bottom of the package at a first angle, and folding underneath the package bottom toward a center of the bottom of the package to form a second lead foot having a reverse gull wing shape, whereupon the portion of the second lead along the side of the package and the portion of the lead along the bottom of the package form an angle of less than 90° from each other and the second lead foot being inclined at a second angle relative to an underlying planar PC board to promote solder wetting, wherein a first side of the die is in contact with the first side

of the diepad proximate to the first and second lead feet, and wherein a first end of the bondwire is in contact with a side of the enclosed lead portion proximate to the first and second lead feet, and a second end of the bondwire is in contact with a second side of the die proximate to the first and second lead feet.

2. (Original) The package of claim 1 wherein the die is one of a power device, a discrete device, and an integrated circuit.

3. (Canceled)

4. (Previously Presented) The package of claim 1 wherein the package has a reduced package profile including the first lead.

5. (Previously Presented) The package of claim 1 wherein the first lead foot is inclined at the second angle between 1° and 7° relative to the planar PC board.

6. (Previously Presented) The package of claim 1 wherein the package body further comprises a notch configured to receive a portion of the first lead foot, thereby permitting the lead foot to be partially recessed within the package body in order to reduce a height of the package.

7. (Previously Presented) The package of claim 6 wherein the notch includes a depth of about two-thirds a thickness of the first lead.

8. (Withdrawn) A small footprint semiconductor device package comprising:  
a package body enclosing a die having an area; and  
a lead including an enclosed portion enclosed by the package body and in electrical communication with the die, and an exposed portion of the lead extending from the side of the package body and folding back along the side of the package toward the bottom of the package, and folding toward a center of the bottom of the package to form a lead foot, a combined width and length of the package body and the exposed lead portion defining a lateral footprint area, such that the die area occupies 40% or more of the footprint area .

9. (Withdrawn) The package of claim 8 wherein the exposed portion of the lead folds toward a center of the bottom of the package to form a rounded lead foot exhibiting a clearance from an underlying PC board defined by a radius of curvature of the foot.

10. (Withdrawn) The package of claim 8 wherein the exposed portion of the lead folds toward a center of the bottom of the package to form a linear lead foot inclined at a second angle relative to an underlying PC board.

11. (Withdrawn) The package of claim 10 wherein the package body exhibits a thickness 90% or greater than a vertical profile of the package.

12. (Withdrawn) A small footprint semiconductor device package comprising:  
a package body enclosing a die having an area; and  
a lead including,

an enclosed portion by the package body, the enclosed portion integral with a die pad supporting the die, the enclosed portion in electrical communication with the die, and

an exposed portion of the lead extending from the side of the package body, folding back along the side of the package toward the bottom of the package, and folding toward a center of the bottom of the package to form a lead foot; a combined width and length of the package body and the exposed lead portion defining a lateral footprint area,

such that the die area occupies about 40% or more of the footprint area and the enclosed lead portion draws heat away from the operating die to the exposed lead portion, with the exposed lead portion dissipating the heat.

13.-15. (Canceled).